

## AMENDMENTS TO THE SPECIFICATION

Please replace paragraphs 0016 and 0017 with the following marked-up replacement paragraphs 0016 and 0017, as follows:

[0016] The housing 10 has a bottomless cover 26, which is made of a material having the capability of withstanding high temperatures, preferably cast aluminum for heat sink capabilities. Cover 26 houses the component circuits 16-24. The cover 26 may or may not be partitioned 25 to house the component circuits 16-24. The substrates for the components 16, 18, 20 and 22 are usually thermally conductive substrates, therefore the cover 26 should have heat sink capabilities. The fourth, and bottom side 28 of the housing 10 is a high temperature plastic material having at least one row of pins 30 molded therein. The pins 30 provide interconnect capabilities between the peripheral components 16-24 and the printed circuit board 12. The pins should preferably be wire bond 44 compatible for connection to the peripheral component circuits 16-24 inside the cover 26 and solderable externally for interconnection to the printed circuit board. The housing 10 is preferably mechanically mounted to the printed circuit board.

[0017] The bottom section ~~26~~28 of the housing 10 is made from a material having heat sink capabilities, preferably molded from a high heat plastic. A raised bead, or track 32 is molded around the periphery of the bottom section 28 for being received by a groove 34 cast in the heat sink cover 26. An adhesive (not shown) may be applied in the groove 34 to attach and seal the bottom section 28 to the cover 26, further protecting the sensitive components from the external environment.